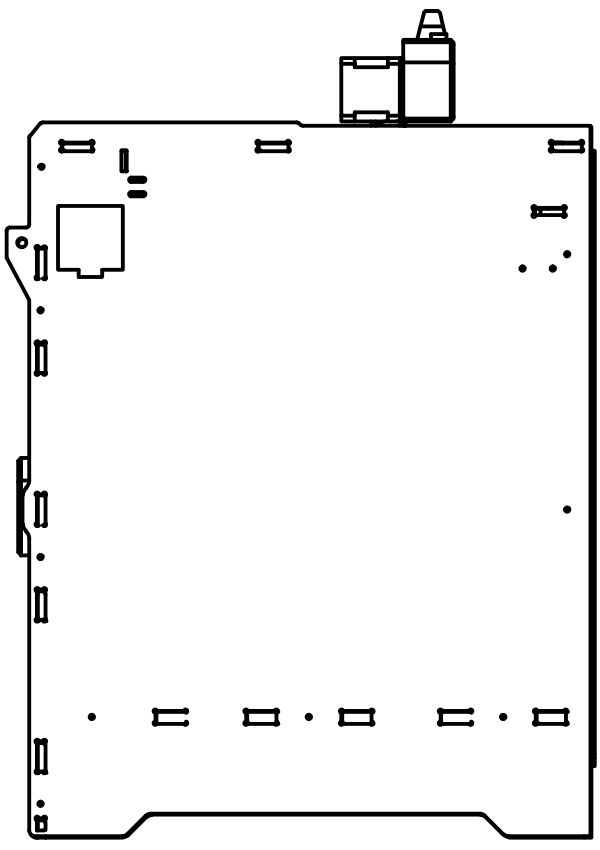
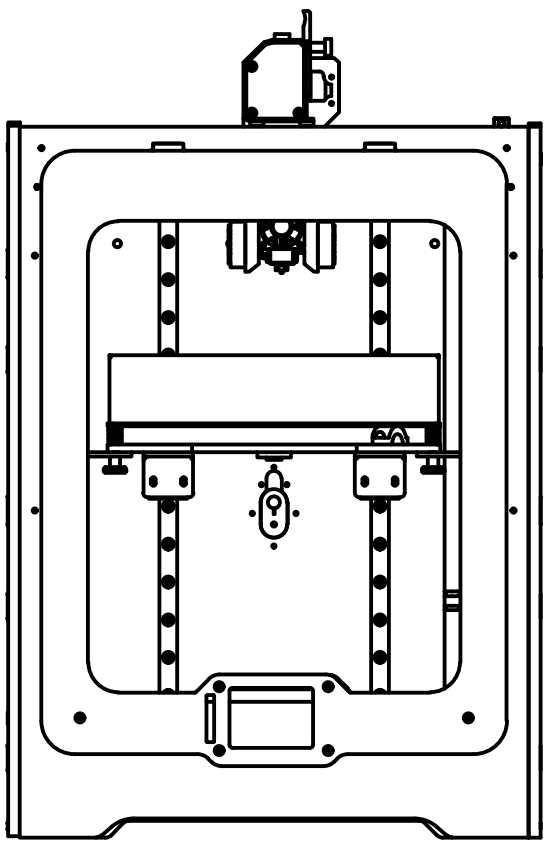
3DPrint.ID
Subsolid X mk.IV

Specification Sheet



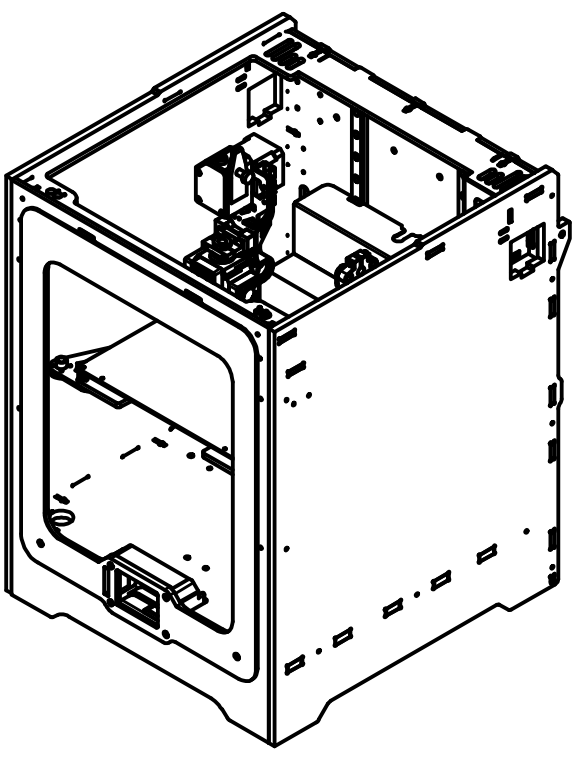


Printer and printing properties

Technology	Fused Deposition Modeling (FDM)
Print head	CORE™ Swappable Printhead
Build volume	200 x 195 x 230mm
Filament diameter	1.75 mm
Layer resolution	0.40 mm nozzle: 200 to 20 micron
XYZ accuracy	12.5, 12.5, 5 micron
Print head travel speed	30 to 150 mm/s
Build speed	0.40 mm nozzle: up to 16 mm3/s
Build plate	Glass build plate / Swappable Build Plate
Build plate temperature	50 to 80 °C
Build plate leveling	Assisted Mesh leveling process
Supported materials	PLA, ABS, CPE, CPE+, PC, Nylon, TPU 95A
Nozzle diameter	Included are 0.25, 0.4, 0.6 and 0.8 mm nozzles
Nozzle temperature	180 to 250 °C
Nozzle heat up time	~ 2 minute
Build plate heat up time	< 6 minutes
Operating sound	50 dBA
Connectivity	Standalone 3D printing from SD Card
Interface	24" TFT Resistive Touch Screen
Additional	Power Failure Resume Printing

Physical Dimensions

Dimensions	321 x 346 x 388 mm
Dimensions (with spool holder)	321 x 446 x 388 mm
Nett weight	11,3 kg
Shipping weight	18,5 kg
Shipping box dimensions	390 x 400 x 565 mm



Power Requirements

Input	220V 4A, 50-60Hz 360W max.
Output	12V DC, 9.2 A

Software

Supplied Software	Cura for Subsolid (free)
Recommended Software	Simplify3D (US$149)
Supported OS	macOS, Windows
File Types	STL and OBJ

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